

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier Nexperia B.V.		User Part Number						
		PESD3V3X2UT						
Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		Part Description						
		NXP ICN8 Protection INDI						
		SMD package						
		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
	TEST							
	Pre- and Post-Stress							
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
		JESD22-A113	241					
	PC	Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85%	24 hours 168 hours					
# A1	Preconditioning	Reflow soldering	3 cycles	524	22940	0		
# A1		MIL-STD-750-1	,	J2 1	22310	<u> </u>		
	HTRB	M1038 Method A						
	High Temperature Reverse	Tj = Tjmax, Vr = 100% of max. datasheet						
# B1	Bias	reverse voltage	1000 hours	30	1280	0		
	TC Temperature Cycling	JESD22-A104 -65 °C to Timax, not to exceed 150°C		. = -		_		
# A4	remperature Cycling	-63 °C to Timax, not to exceed 130°C	1000 cycles	156	7080	0		
	UHAST	JESD22-A118						
# A3 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %	— 96 hours	156	7080	0		
		JESD22-A102						
	AC	Tamb = 121 °C, RH = 100 %						
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)						
		JECD22 4101						
	H3TRB High Humidity High	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of						
# A2 alt		rated reverse voltage ^[1]	1000 hours	156	7080	0		
# AZ dIL	. cperatare neverse blas	MIL-STD-750 Method 1037	1000 110015	130	7000	U		
	IOL	ton = toff, devices powered to insure ΔT_j =						
# A5	Intermittent Operating Life		1000 hours	n.a.	n.a.	n.a.		
	RSH	JESD22-A111						
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	56	1700	0		
" 616	SD Solderability	J-STD-002		56	1700	•		
# C10	Soluerability	7-010-012		56	1700	0		

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
NXP ICN8	Protection INDI	1280	0	3,32	3,01E+08

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